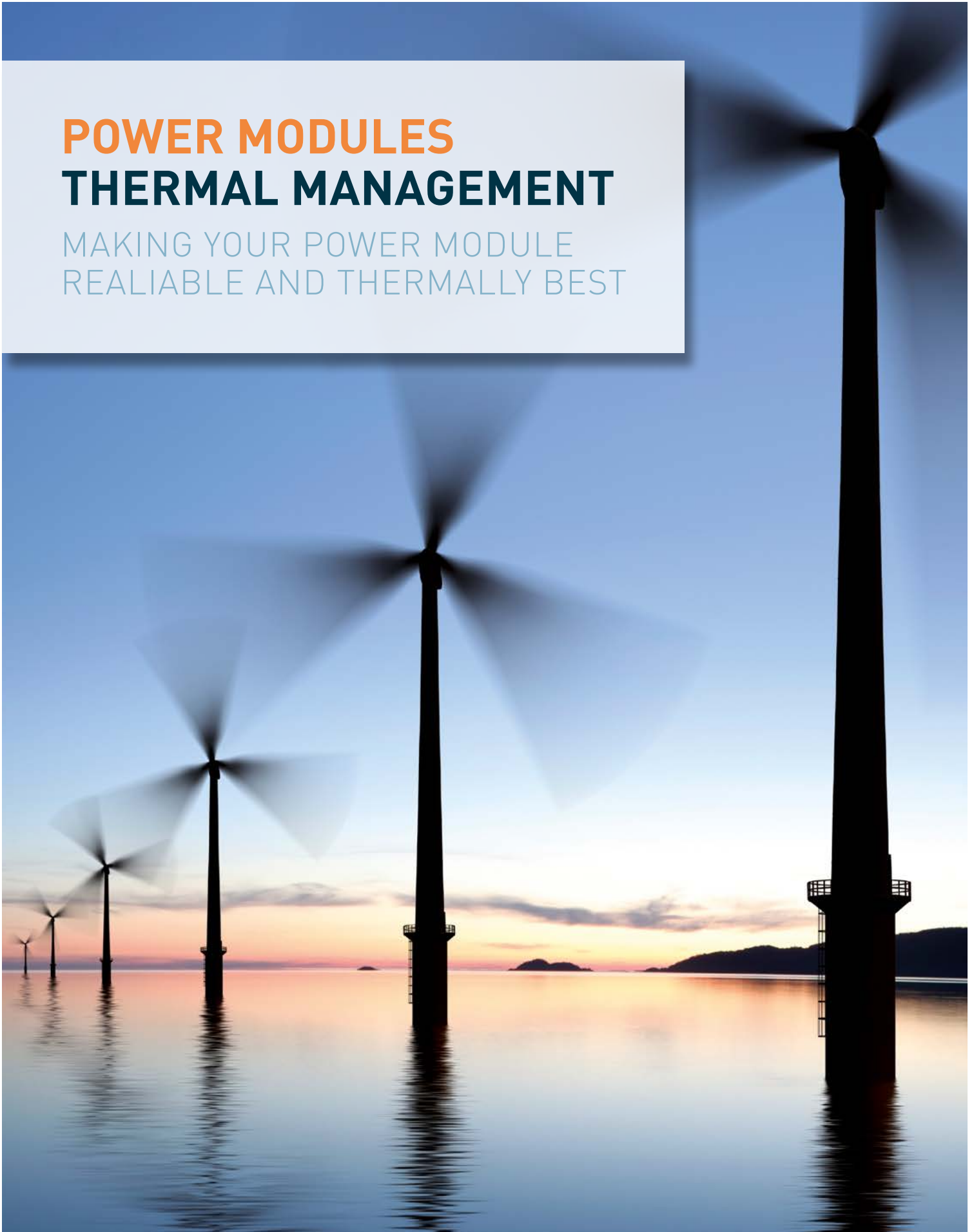


POWER MODULES **THERMAL MANAGEMENT**

MAKING YOUR POWER MODULE
REALIABLE AND THERMALLY BEST



POWER MODULES THERMAL MANAGEMENT



MAKING YOUR POWER MODULE RELIABLE AND THERMALLY BEST

MODULAR CONCEPTS

HALA High Performing Contacting Interface Materials

Phase Change films

- TPC-Y-PC
- TPC-W-PC
- TPC-T-AL-CB
- TPC-R-AL
- TPC-V-PG-CB

Phase Change printable

- TPC-Z-PC-HT-M/-E
- TPC-X-PC-NC-HT-M/-E

Graphite foil

- TFO-S-CB

Graphite foil / pyrolytic

- TFO-Y-PG
- TFO-V-PG
- TFO-ZS-PG

Silicone foil

- TEL-Z-SI

- TEL-ZS-SI

Silicone grease

- TGR-S-SI

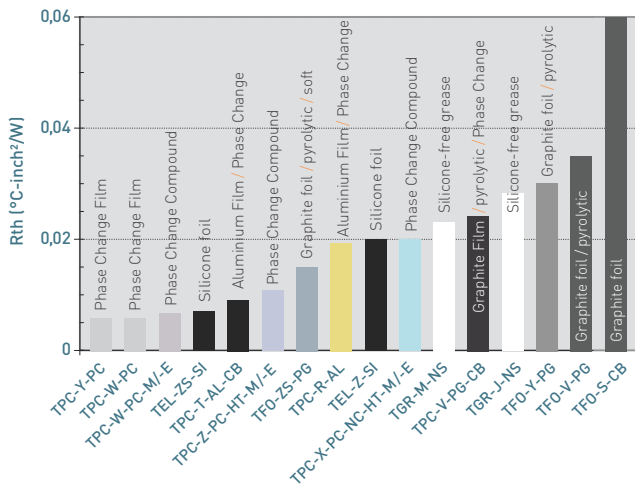
Silicone-free grease

- TGR-J-NS
- TGR-M-NS

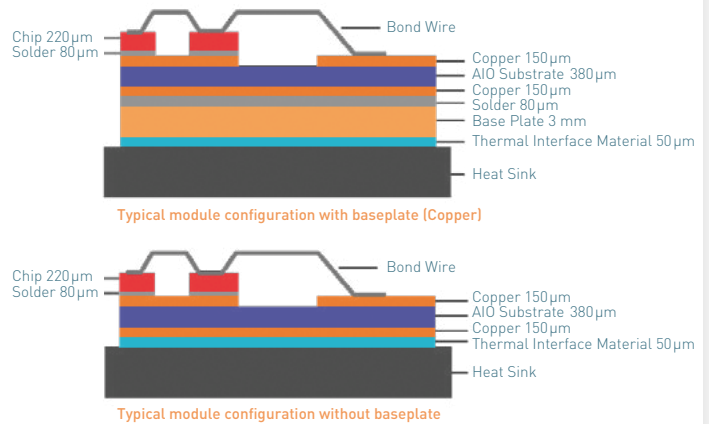


Release 03 / 2024

ΔT DATA



CONSTRUCTION DIAGRAM



CREATING

- Maximum thermal contact
- Minimized thermal resistance
- Compensating mechanic tolerances
- Enhancing efficiency

BENEFITS

- Increasing long-term reliability
- Minimizing chip temperatures
- Homogenizing chip temperatures
- Pre-applied dry-to-the-touch



Vincotech Module

All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.